



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Christo P. Bojkov, et al.

Art Unit: 2811

Serial No.: 10/678,709

Examiner: TBD

Filed: 10/03/03

Docket: TI-35797

For: Sealing and Protecting Integrated Circuit Bonding Pads

LETTER TO THE OFFICIAL DRAFTSPERSON

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Karen Vertz  
Karen Vertz

6-18-04  
Date

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Enclosed are **THREE (3)** sheets of formal drawings for the above-referenced case. Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments Incorporated. This sheet is enclosed in triplicate.

Texas Instruments Incorporated  
P.O. Box 655474 M/S 3999  
Dallas, Texas 75265  
Phone: (972) 917-5355

Respectfully submitted,

Yingsheng Tung  
Yingsheng Tung  
Reg. No. 52,305  
Attorney for Applicants